



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

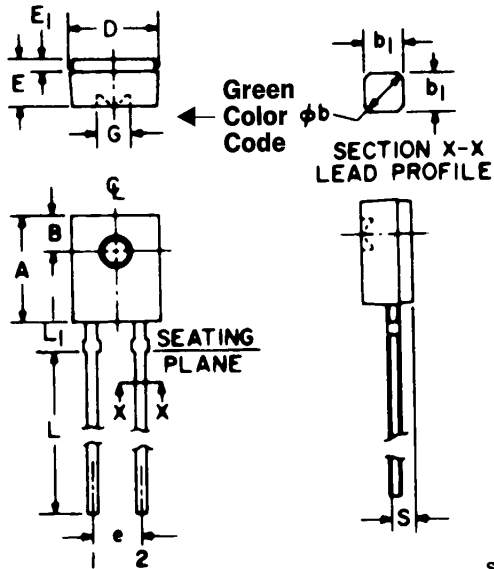
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**PACKAGE DIMENSIONS**



**DESCRIPTION**

The F5G1 is an 880nm LED encapsulated in a clear, wide angle, sidelooper package.

**FEATURES**

- Good optical to mechanical alignment
- Mechanically and wavelength matched to the L14Q series phototransistor
- Plastic package with a color stripe for easy recognition from phototransistor
- High irradiance level

ST1334

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	5.59	5.80	.220	.228	
B	1.78	NOM.	.070	NOM.	2
@b	.60	.75	.024	.030	1
b <sub>1</sub>	.51	NOM.	.020	NOM.	1
D	4.45	4.70	.175	.185	
E	2.41	2.67	.095	.105	
E <sub>1</sub>	.58	.69	.023	.027	
e	2.41	2.67	.095	.105	3
G	1.98	NOM.	.078	NOM.	
L	12.7	—	.500	—	
L <sub>1</sub>	1.40	1.65	.055	.065	
S	.83	.94	.033	.037	3

**PACKAGE OUTLINE**



ST1604

NOTES:

1. TWO LEADS. LEAD CROSS SECTION DIMENSIONS UNCONTROLLED WITHIN 1.27 mm (.050") OF SEATING PLANE.
2. CENTERLINE OF ACTIVE ELEMENT LOCATED WITHIN .25 mm (.010") OF TRUE POSITION.
3. AS MEASURED AT THE SEATING PLANE.
4. INCH DIMENSIONS DERIVED FROM MILLIMETERS.

**ABSOLUTE MAXIMUM RATINGS** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Specified)

Storage Temperature .....	-55°C to +100°C
Operating Temperature .....	-55°C to +100°C
Soldering:	
Lead Temperature (Iron) .....	240°C for 5 sec. <sup>(2,3,4,5)</sup>
Lead Temperature (Flow) .....	260°C for 10 sec. <sup>(2,3,5)</sup>
Continuous Forward Current .....	50 mA
Forward Current (pw, 1μS; ≤ 33 Hz) .....	2 A
Reverse Voltage .....	6 Volts
Power Dissipation .....	100 mW <sup>(1)</sup>

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Specified)

(All measurements made under pulse conditions.)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
Forward Voltage	$V_F$	—		1.7	V	$I_F = 20\text{ mA}$
Reverse Breakdown Voltage	$V_R$	6.0		—	V	$I_R = 10\ \mu\text{A}$
Reverse Leakage Current	$I_R$	—		10	μA	$V_R = 5\text{ V}$
Peak Emission Wavelength	$\lambda_p$		880		nm	$I_F = 100\text{ mA}$
Emission Angle at ½ Power	$\theta$		±35		Degrees	
Radiant Intensity	$I_e$	0.6		—	mW/sr	$I_F = 20\text{ mA}$ <sup>(6)</sup>

**NOTES**

1. Derate power dissipation linearly 1.33 mW/°C above 25°C ambient.
2. RMA flux is recommended.
3. Methanol or Isopropanol alcohols are recommended as cleaning agents.
4. Soldering iron tip 1/16" (1.6 mm) minimum from housing.
5. As long as leads are not under any stress or spring tension.
6.  $I_e$  measured with a 0.45 cm aperture placed 1.6 cm from the tip of the lens on the lens centerline perpendicular to the plane of the leads.

**TYPICAL CHARACTERISTICS**

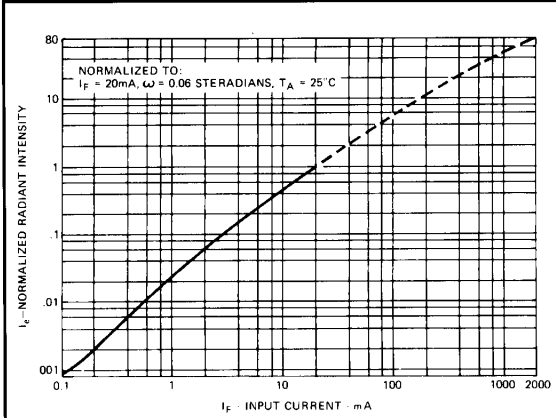


Fig. 1. Radiant Intensity vs. Input Current

ST1041

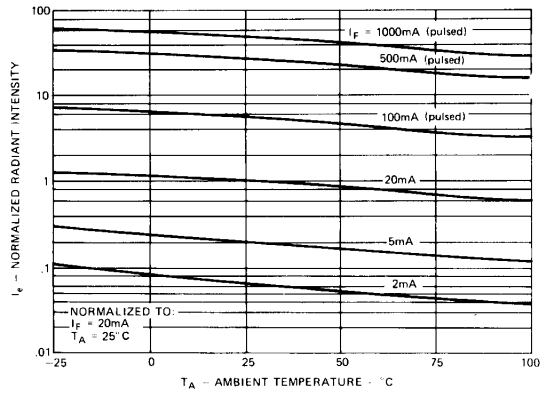


Fig. 2. Radiant Intensity vs. Temperature

ST1046

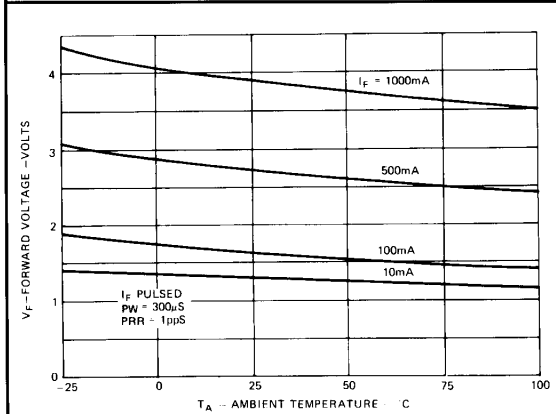


Fig. 3. Forward Voltage vs. Temperature

ST1042

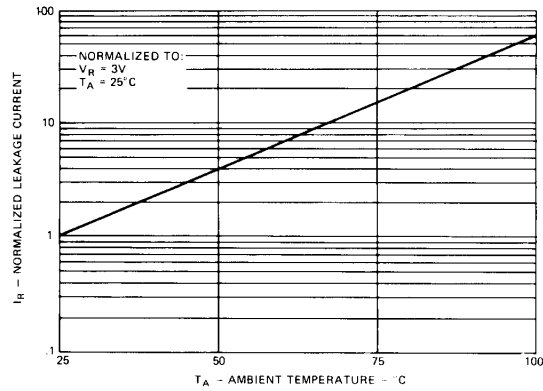


Fig. 4. Leakage Current vs. Temperature

ST1045

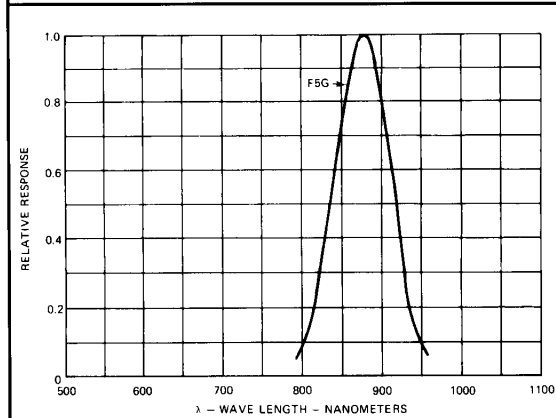


Fig. 5. Spectral Response

ST1043

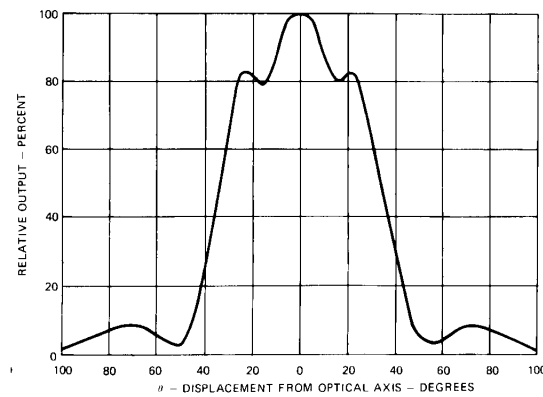


Fig. 6. Typical Radiation Pattern

ST1044



## AIGaAs INFRARED EMITTING DIODE

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